

ABSTRACT

According to the present invention, when a semiconductor element having protruding electrodes formed thereon is connected to a circuit board via conductive resin, stable connection is made even when an electrode pitch is small on the semiconductor element. On semiconductor element package regions on the circuit board, a paste electrode material containing photopolymerizable materials is printed to form a film having a prescribed thickness, and this electrode material film is baked after exposure and development thereof so as to obtain circuit electrodes having edges warped in a direction of going apart from the circuit board surface. Then, the protruding electrodes and the concave surfaces of the circuit electrodes are brought in abutment with each other and connected via the conductive resin which surrounds the abutments between the respective electrodes and is held on the concave surfaces of the circuit electrodes. With this arrangement, the concave surfaces of the circuit electrodes act as saucers and prevent the conductive resin from being squeezed out, thereby eliminating possible occurrence of short circuits.